

SN54LS257B, SN54LS258B, SN54S257, SN54S258 SN74LS257B, SN74LS258B, SN74S257, SN74S258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

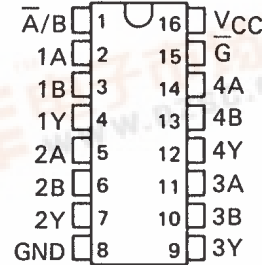
查询"SN54LS257B-SP"供应商

SDLS148 – OCTOBER 1976 – REVISED MARCH 1988

- Three-State Outputs Interface Directly with System Bus
- 'LS257B and 'LS258B Offer Three Times the Sink-Current Capability of the Original 'LS257 and 'LS258
- Same Pin Assignments as SN54LS157, SN74LS157, SN54S157, SN74S157, and SN54LS158, SN74LS158, SN54S158, SN74S158
- Provides Bus Interface from Multiple Sources in High-Performance Systems

SN54LS257B, SN54S257,
SN54LS258B, SN54S258 . . . J OR W PACKAGE
SN74LS257B, SN74S257,
SN74LS258B, SN74S258 . . . D OR N PACKAGE

(TOP VIEW)



	AVERAGE PROPAGATION DELAY FROM DATA INPUT	TYPICAL POWER DISSIPATION†
'LS257B	9 ns	55 mW
'LS258B	9 ns	55 mW
'S257	4.8 ns	320 mW
'S258	4 ns	280 mW

† Off state (worst case)

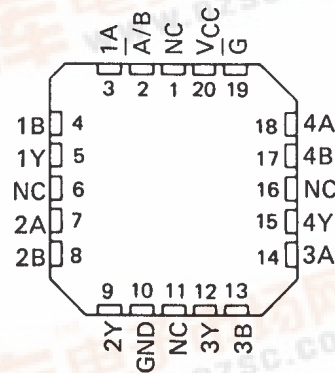
description

These devices are designed to multiplex signals from four-bit data sources to four-output data lines in bus-organized systems. The 3-state outputs will not load the data lines when the output control pin (\bar{G}) is at a high-logic level.

Series 54LS and 54S are characterized for operation over the full military temperature range of -55°C to 125°C ; Series 74LS and 74S are characterized for operation from 0°C to 70°C .

SN54LS257B, SN54S257,
SN54LS258B, SN54S258 . . . FK PACKAGE

(TOP VIEW)



NC-No internal connection.

FUNCTION TABLE

INPUTS				OUTPUT Y	
OUTPUT CONTROL	SELECT	A	B	'LS257B 'S257	'LS258B 'S258
H	X	X	X	Z	Z
L	L	L	X	L	H
L	L	H	X	H	L
L	H	X	L	L	H
L	H	X	H	H	L

H = high level, L = low level, X = irrelevant,
Z = high impedance (off)

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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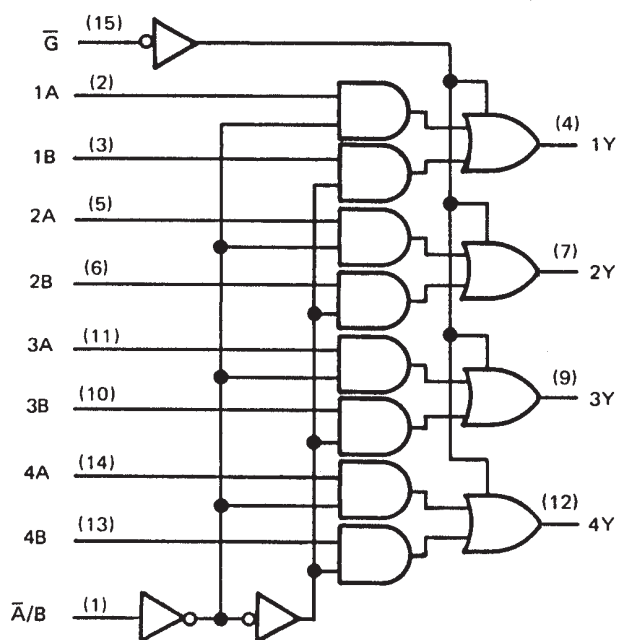
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SN54LS257B, SN54LS258B, SN54S257, SN54S258 SN74LS257B, SN74LS258B, SN74S257, SN74S258 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

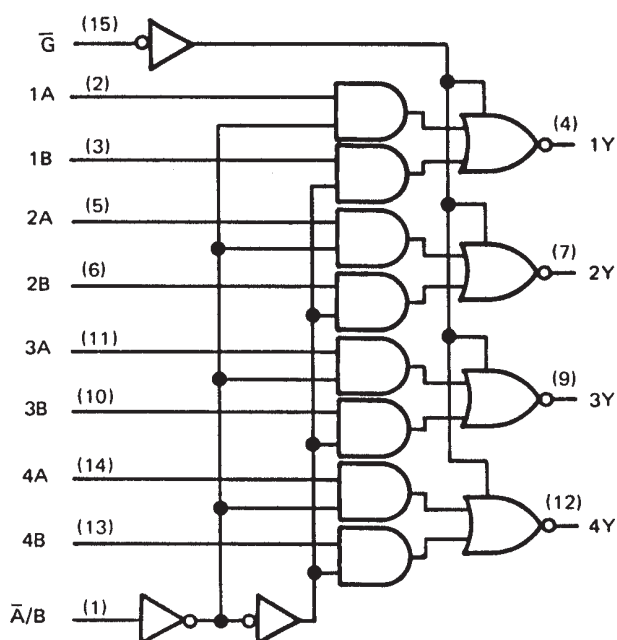
SDLS 257, 258, 54LS257, 54LS258, 74LS257, 74LS258, 54S257, 54S258, 74S257, 74S258
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logic diagrams (positive logic)

'LS257B, 'S257

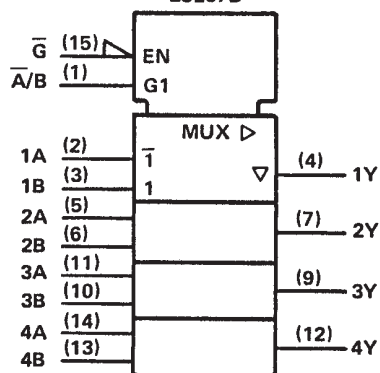


'LS258B, 'S258

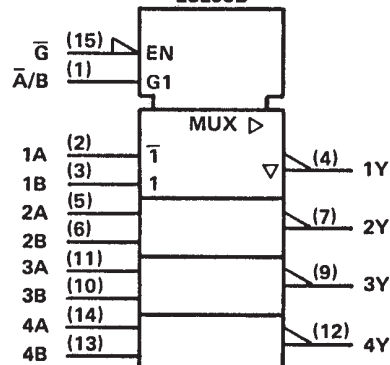


logic symbols†

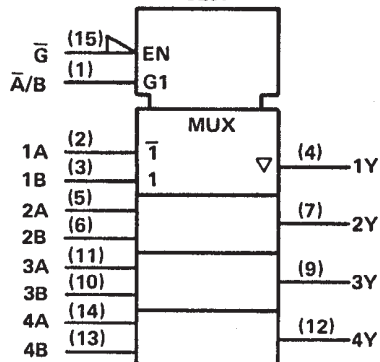
'LS257B



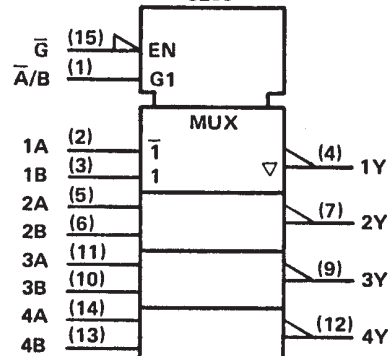
'LS258B



'S257



'S258



†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

SDLS 查詢 CME 925-7R REVISED 11/1988 11/1988

	SN54LS'			SN74LS'			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V _{IH} High-level input voltage	2			2			V
V _{IL} Low-level input voltage			0.7			0.8	V
I _{OH} High-level output current			− 1			− 2.6	mA
I _{OL} Low-level output current			12			24	mA
T _A Operating free-air temperature	− 55		125	0		70	°C

PARAMETER		TEST CONDITIONS†	SN54LS'		SN74LS'		UNIT
			MIN	TYP‡ MAX	MIN	TYP‡ MAX	
V_{IK}		$V_{CC} = \text{MIN}, I_I = -18 \text{ mA}$		-1.5		-1.5	V
V_{OH}		$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = \text{MAX}, I_{OH} = \text{MAX}$	2.4	3.4	2.4	3.1	V
V_{OL}		$V_{CC} = \text{MIN}, V_{IH} = 2 \text{ V}, V_{IL} = \text{MAX},$	$I_{OL} = 12 \text{ mA}$		0.25 0.4		V
			$I_{OL} = 24 \text{ mA}$		0.35 0.5		
I_{OZH}		$V_{CC} = \text{MAX}, V_{IH} = 2 \text{ V}, V_O = 2.7 \text{ V}$	20		20		μA
I_{OZL}		$V_{CC} = \text{MAX}, V_{IH} = 2 \text{ V}, V_O = 0.4 \text{ V}$	-20		-20		μA
I_I		$V_{CC} = \text{MAX}, V_I = 7 \text{ V}$	0.1		0.1		mA
I_{IH}		$V_{CC} = \text{MAX}, V_I = 2.7 \text{ V}$	20		20		μA
I_{IL}		$V_{CC} = \text{MAX}, V_I = 0.4 \text{ V}$	-0.4		-0.4		mA
$I_{OS} \S$		$V_{CC} = \text{MAX},$	-30	-130	-30	-130	mA
I_{CC}	All outputs high	$V_{CC} = \text{MAX},$ See Note 2	'LS257B	8 12	8 12	mA	
	All outputs low			12 18	12 18		
	All outputs off			13 19	13 19		
	All outputs high		'LS258B	6 9	6 9		
	All outputs low			10 15	10 15		
	All outputs off			11 16	11 16		

switching characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $R_L = 667\ \Omega$

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS257B			'LS258B			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
tPLH	Data	Any	CL = 45 pF, See Note 3	8 13			7 12			ns
tPHL				10 15			11 17			
tPLH	Select	Any		16 21			14 21			ns
tPHL				17 24			19 24			
tPZH	Output Control	Any		15 30			15 30			ns
tPZL				19 30			20 30			
tPHZ	Output Control	Any	CL = 5 pF, See Note 3	18 30			18 30			ns
tPLZ				16 25			16 25			

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

查询"SN54LS257B-SP"供应商

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recommended operating conditions

	SN54S'			SN74S'			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}			-2			-6.5	mA
Low-level output current, I_{OL}			20			20	mA
Operating free-air temperature, T_A	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†	'S257			'S258			UNIT		
				MIN	TYP‡	MAX	MIN	TYP‡	MAX			
V _{IH}	High-level input voltage					2		2		V		
V _{IL}	Low-level input voltage							0.8		V		
V _{IK}	Input clamp voltage		V _{CC} = MIN, I _I = −18 mA					−1.2		V		
V _{OH}	High-level output voltage		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = −1 mA	SN74S'	2.7			2.7			V	
			V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = MAX	SN54S'	2.4	3.4	2.4 3.4					
				SN74S'	2.4	3.2	2.4 3.2					
V _{OL}	Low-level output voltage		V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OL} = 20 mA			0.5			0.5			V
I _{OZH}	Off-state output current, high-level voltage applied		V _{CC} = MAX, V _{IH} = 2 V, V _O = 2.4 V			50			50			μA
I _{OZL}	Off-state output current, low-level voltage applied		V _{CC} = MAX, V _{IH} = 2 V, V _O = 0.5 V			−50			−50			μA
I _I	Input current at maximum input voltage		V _{CC} = MAX, V _I = 5.5 V			1			1			mA
I _{IH}	High-level input current	S input	V _{CC} = MAX, V _I = 2.7 V			100			100			μA
		Any other				50			50			
I _{IL}	Low-level input current	S input	V _{CC} = MAX V _I = 0.5 V			−4			−4			mA
		Any other				−2			−2			
I _{OS}	Short-circuit output current §		V _{CC} = MAX			−40	−100	−40	−100	mA		
I _{CC}	Supply current	All outputs high	V _{CC} = MAX, See Note 2			44	68	36	56	mA		
		All outputs low				60	93	52	81			
		All outputs off				64	99	56	87			

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$.

§ Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

NOTE 2: I_{CC} is measured with all outputs open and all possible inputs grounded while achieving the stated output conditions.

switching characteristics, $V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}, R_L = 280 \Omega$

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'S257			'S258			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
tPLH	Data	Any	CL = 15 pF, See Note 3	5	7.5		4	6	ns	
tPHL				4.5	6.5		4	6		
tPLH	Select	Any		8.5	15		8	12	ns	
tPHL				8.5	15		7.5	12		
tPZH	Output	Any		13	19.5		13	19.5	ns	
tPZL	Control			14	21		14	21		
tPHZ	Output	Any	CL = 5 pF, See Note 3	5.5	8.5		5.5	8.5	ns	
tPLZ	Control			9	14		9	14		

¶ f_{max} = Maximum clock frequency

t_{PLH} = propagation delay time, low-to-high-level output

t_{PHL} = propagation delay time, high-to-low-level output

t_{PZH} = output enable time to high level

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

t_{PZL} = output enable time to low level

t_{PHZ} = output disable time from high level

t_{PLZ} = output disable time from low level



PACKAG

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Pe
5962-7603701VEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
5962-7603701VFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
5962-7603701VFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
7603701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
7603701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
7603701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
7603701FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
76038012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg
76038012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg
7603801EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
7603801EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
7603801FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
7603801FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
8002301EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
8002301EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
8002301FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
8002301FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
JM38510/07906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
JM38510/07906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
JM38510/07906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
JM38510/07906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
JM38510/30906B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg
JM38510/30906B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg
JM38510/30906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
JM38510/30906BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
JM38510/30906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
JM38510/30906BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
SN54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SN54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SN54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg



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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Pea
SN54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SN54S257J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SN54S257J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SN54S258J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SN54S258J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SN74LS257BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
SN74LS257BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
SN74LS257BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS257BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS257BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg



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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Pea
SN74LS257BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
SN74LS257BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS257BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600



PACKAGING

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak
SN74LS258BDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
SN74LS258BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
SN74LS258BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS258BN3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS258BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
SN74LS258BNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
SN74LS258BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74LS258BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-2600
SN74S257N	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
SN74S257N	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
SN74S257N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S257N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S257NE4	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
SN74S257NE4	NRND	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg
SN74S258DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74S258DR	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74S258N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S258N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S258N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74S258N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SNJ54LS257BKF	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg



Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Pea
SNJ54LS257BFB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg
SNJ54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SNJ54LS257BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SNJ54LS257BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
SNJ54LS257BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
SNJ54LS258BFB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg
SNJ54LS258BFB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg
SNJ54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SNJ54LS258BJ	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SNJ54LS258BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
SNJ54LS258BW	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
SNJ54S257FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg
SNJ54S257FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg
SNJ54S257J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SNJ54S257J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SNJ54S257W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
SNJ54S257W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
SNJ54S258FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg
SNJ54S258FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg
SNJ54S258J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SNJ54S258J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg
SNJ54S258W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg
SNJ54S258W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com> for more information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.



www.ti.com

PACKAG

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardant in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54LS257B, SN54LS257B-SP, SN54LS258B, SN54S257, SN54S258, SN74LS257B, SN74LS258B, SN74S257, SN74S258

● Catalog: [SN74LS257B](#), [SN54LS257B](#), [SN74LS258B](#), [SN74S257](#), [SN74S258](#)

● Military: [SN54LS257B](#), [SN54LS258B](#), [SN54S257](#), [SN54S258](#)

● Space: [SN54LS257B-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS257BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS257BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS258BDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS258BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



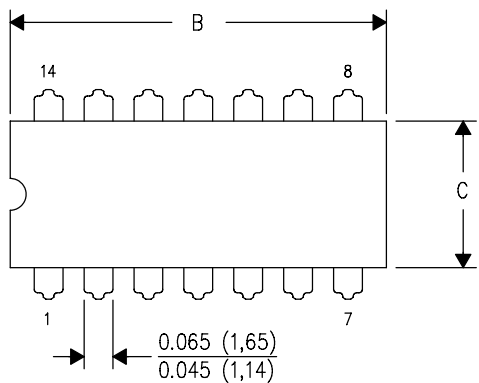
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS257BDR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS257BNSR	SO	NS	16	2000	346.0	346.0	33.0
SN74LS258BDR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS258BNSR	SO	NS	16	2000	346.0	346.0	33.0

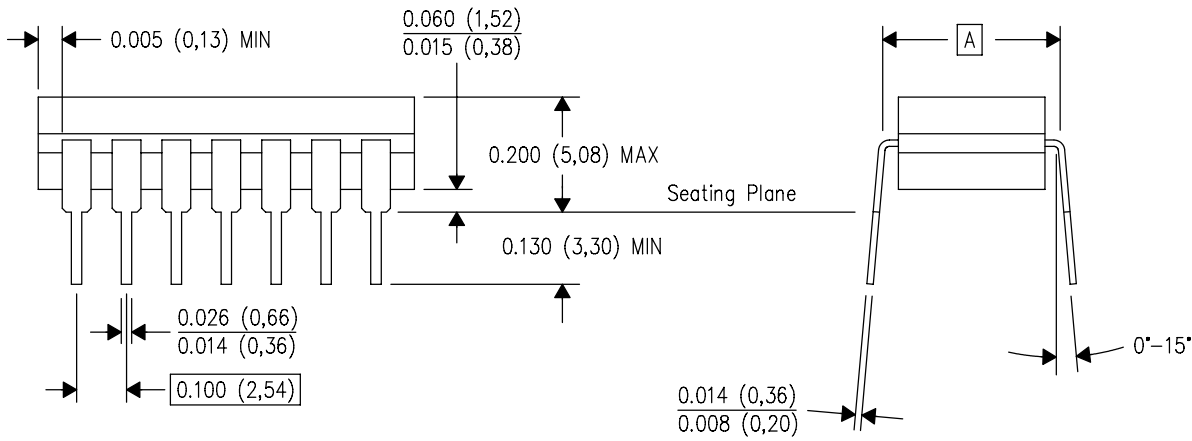
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

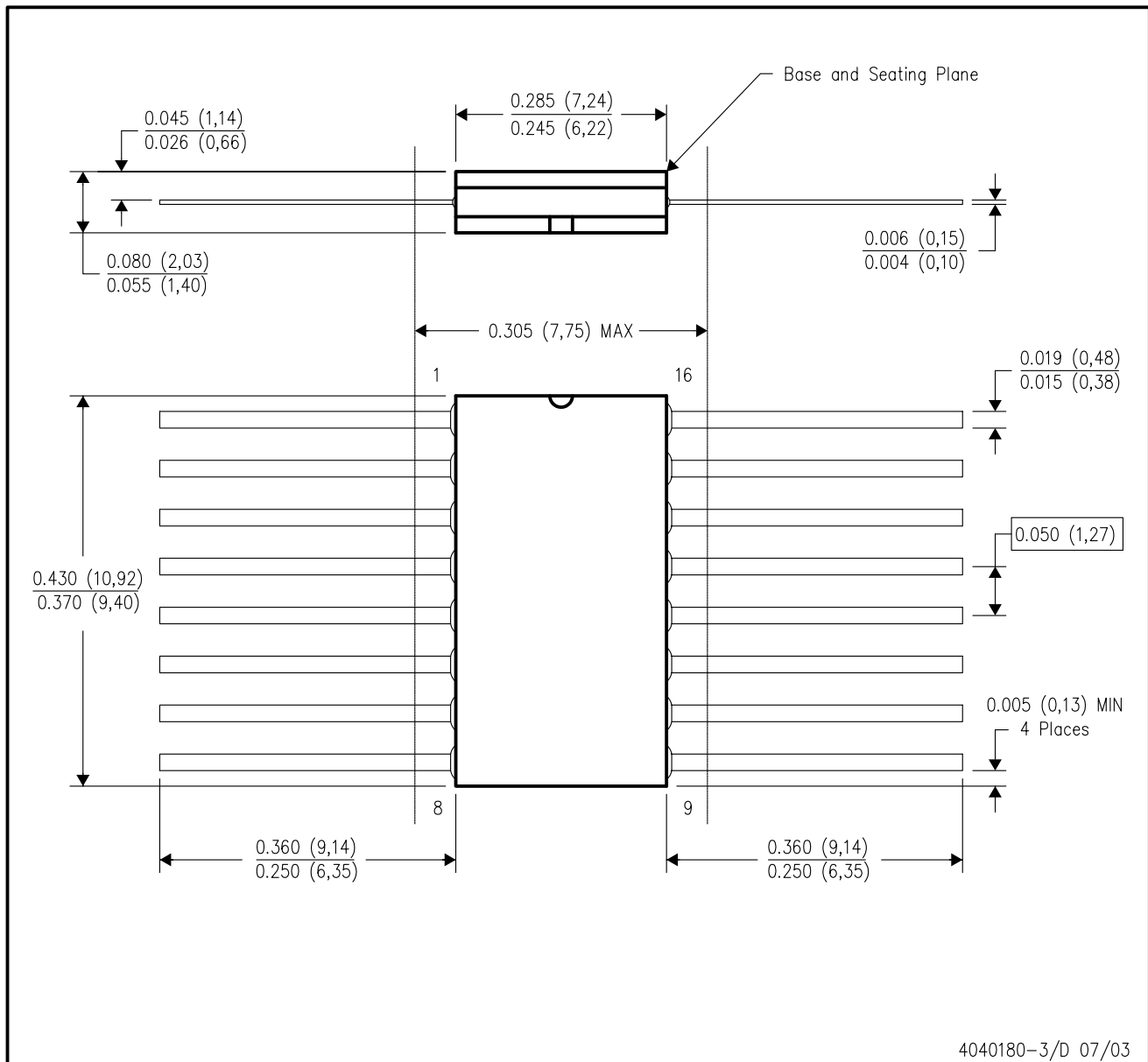


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK

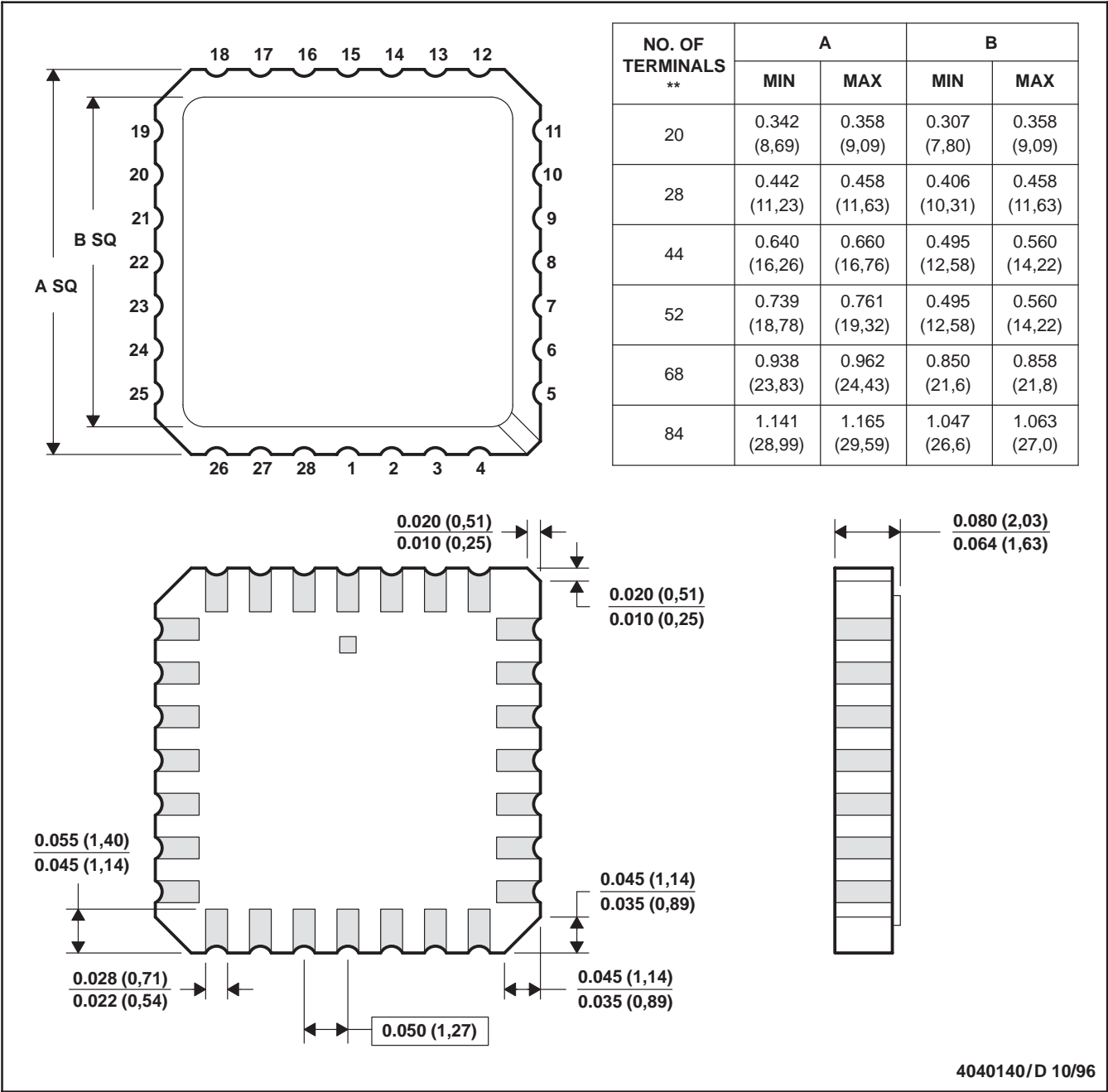


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

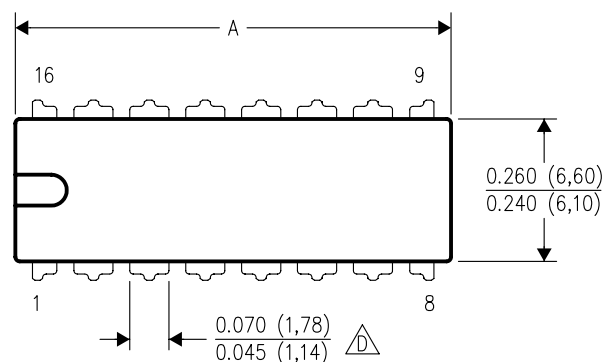
LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

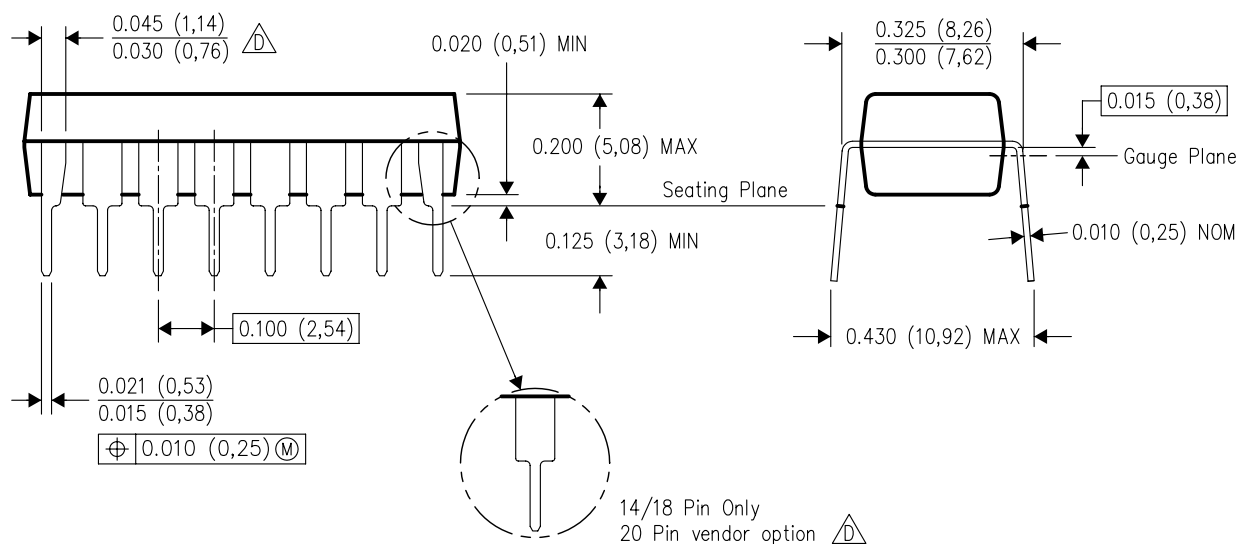


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004



16 PINS SHOWN



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD

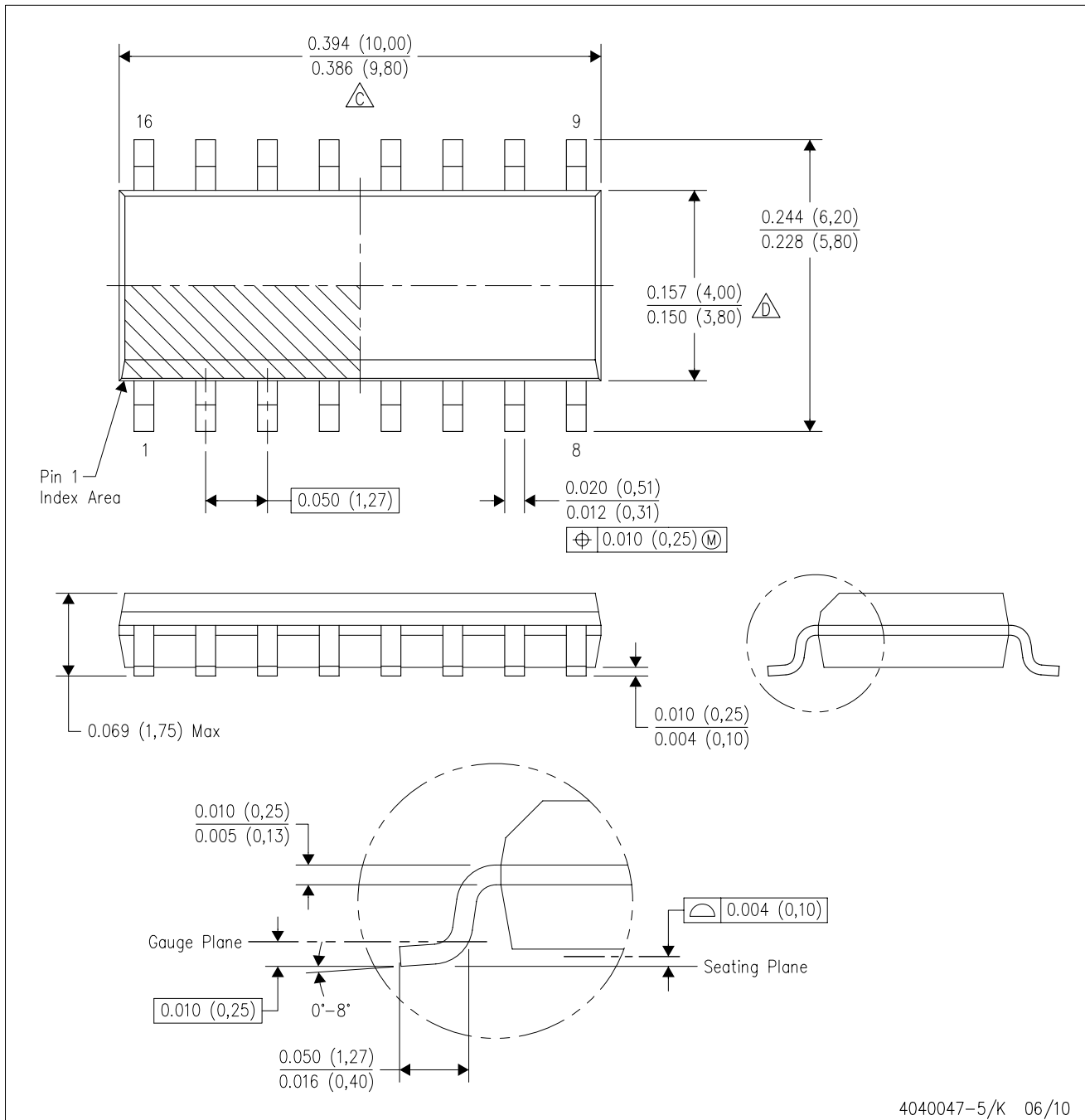


4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

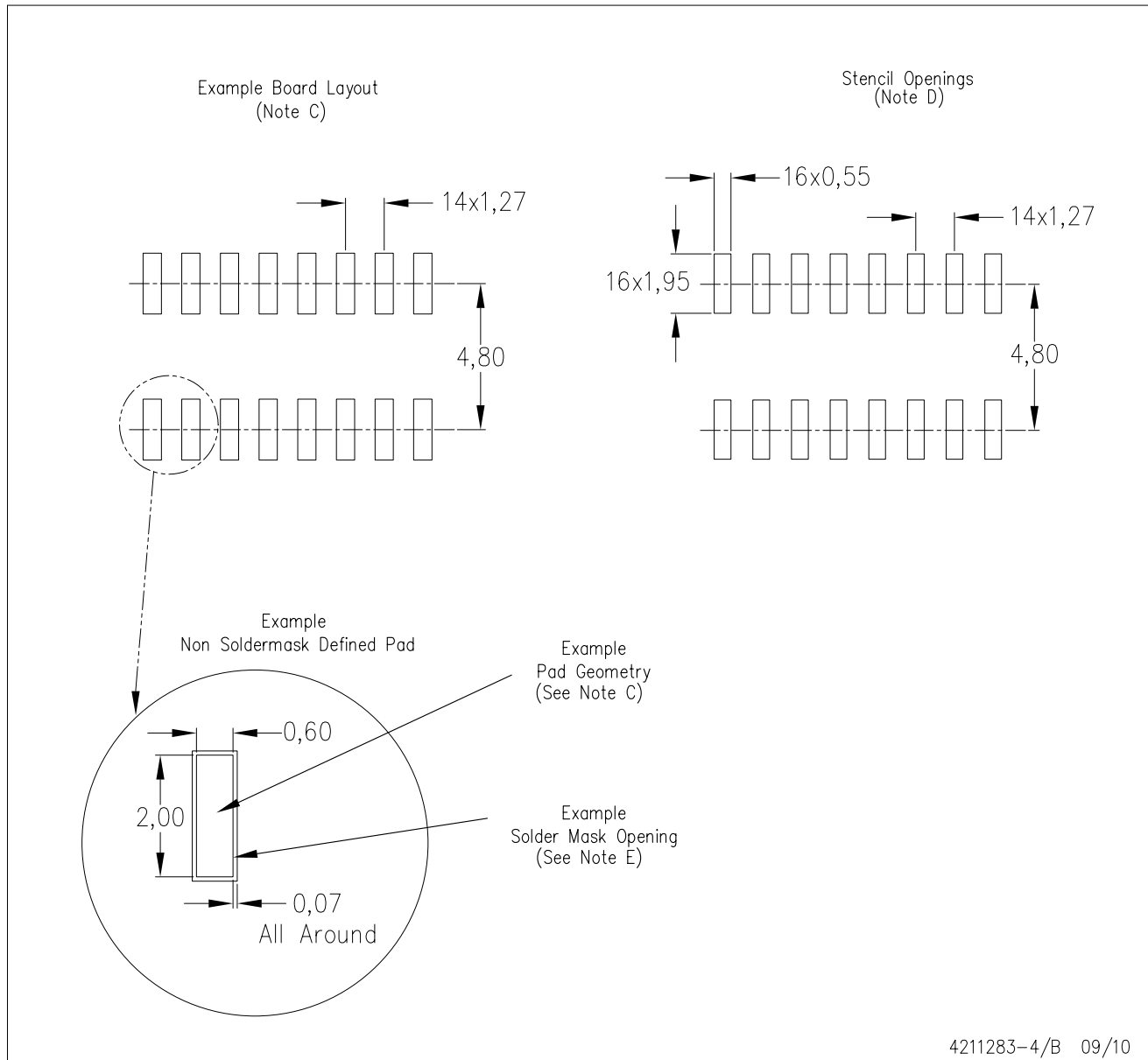
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



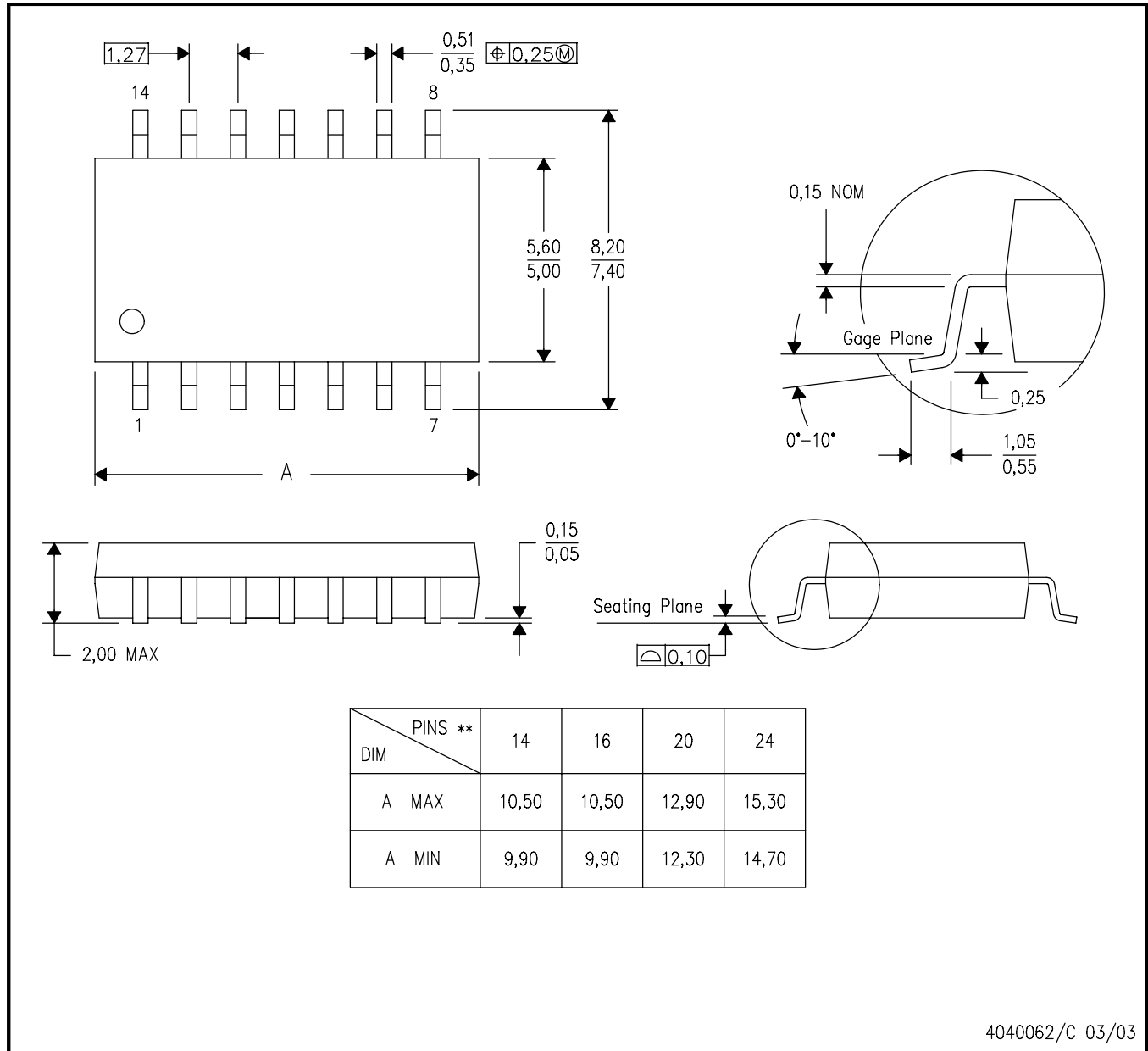
- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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